

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#13 / B
D. EVANS
9.20.03

In re Application of: Tan, Aik Chong et al.
Serial No.: 09/736,462
Filing Date: December 12, 2000
Group Art Unit: 2831
Examiner: NGO, HUNG V
Title: BUMP CHIP LEAD FRAME AND PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING FACSIMILE
TRANSMITTED TO THE PATENT AND TRADEMARK OFFICE, ATTN EXAMINER
NGO, HUNG V AT THE FAX NO. (703) 872-9319

ON: July 8, 2002
Date of Facsimile Transmission

11 pages

Lydia McNamara
Name of Person Signing Certificate

Lydia McNamara 7/8/2002
SIGNATURE DATE

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JAN 14 2003

Honorable Commissioner of Patents,
Washington, D.C. 20231

TECHNOLOGY CENTER 2800

AMENDMENT AFTER FINAL ACTION PURSUANT TO 37 C.F.R. § 1.116

SIR:

In response to the office action mailed May 9, 2002,
Applicants respectfully request that the Examiner
reconsider and further examine the application in view of
the following amendments and/or comments.